

**'98 マイクロマシン訪米調査団
調査報告書**

平成11年3月

財団法人マイクロマシンセンター

はじめに

マイクロマシン技術は次世代の基盤技術として注目されており、世界の大学、研究機関、あるいは企業において活発な研究開発が行われています。財団法人マイクロマシンセンターは1992年1月に設立以来、マイクロマシン技術の基盤を確立し、マイクロマシンが社会において広く普及することを目指して活動しています。

当センターの事業の一つに国際交流事業があり、その中核をなす一つとして海外への調査団の派遣があります。調査団は国際学会あるいは海外との交流セミナーに参加し、また同時に周辺研究機関を訪問し技術動向を調査すると共に、技術者間の交流を図ることを主たる目的としてきました。今回の調査団は、本年1月17日～21日にアメリカ・フロリダ州オーランドで開催された12th IEEE International Micro Electro Mechanical Systems Conference (MEMS'99)に参加すると共に、アメリカの研究機関を訪問しました。

MEMS'99の参加者は、529名（昨年のハイデルベルグMEMS'98は約670名）、発表件数は113件で、日本からの発表は30件と約1/4を占め、産技プロジェクト関係では6件の発表が行われました。主催国のアメリカ（48件）を除くと日本からの発表件数は群を抜いており、世界の中での日本のマイクロマシン技術が大きなウェイトを占めていることが分かりました。

調査団はMEMS'99に参加した後、ジョージア州アトランタにある Georgia Institute of Technology とカリフォルニア州バークレーにある University of California, Berkeley を訪問しました。訪問先では当センターの活動を紹介し、また訪問先の活動紹介を受け、更にこれらに関し活発な討論を行い、これらを通じて相互の技術交流を図ることができました。

この報告書は調査団のメンバーが分担して上記の調査内容をまとめたものです。この調査結果が参加した調査団員の今後の研究開発活動に生かされるだけでなく、マイクロマシンセンターの各種の事業活動に生かされることを願っています。また調査団員が11日間にわたって行動をともし、親交を深めたことは今後の研究開発の円滑な推進に大きく貢献することと期待する次第です。

最後に、団員各位のご協力と関係各位のご高配に深く感謝いたします。

平成11年3月

98マイクロマシン訪米調査団
事務局
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